

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re The Application of:)
 David Chong Sook Lim et al.)
)
Serial No.: 10/664,982)
)
Filed: September 17, 2003)
)
For: PACKAGING SYSTEM FOR)
 DIE-UP CONNECTION OF A)
 DIE-DOWN ORIENTED INTE-)
 GRATED CIRCUIT)

Examiner: Leonardo Andujar

Art Unit: 2826

Cesari and McKenna, LLP
88 Black Falcon Avenue
Boston, MA 02210
May 22, 2007

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT

In response to the Office action dated 2/28/2007, please consider the following.